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[54] **METHOD FOR FABRICATING SELF-ASSEMBLING MICROSTRUCTURES**

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[52] **U.S. Cl.** **156/655.1**; 156/626; 156/633; 156/649; 156/657; 156/662; 156/631; 437/8; 437/86; 437/209; 437/226

[58] **Field of Search** 156/626, 627, 156/633, 649, 655, 657, 662, 631; 437/8, 180, 086, 209, 225, 226; 29/592

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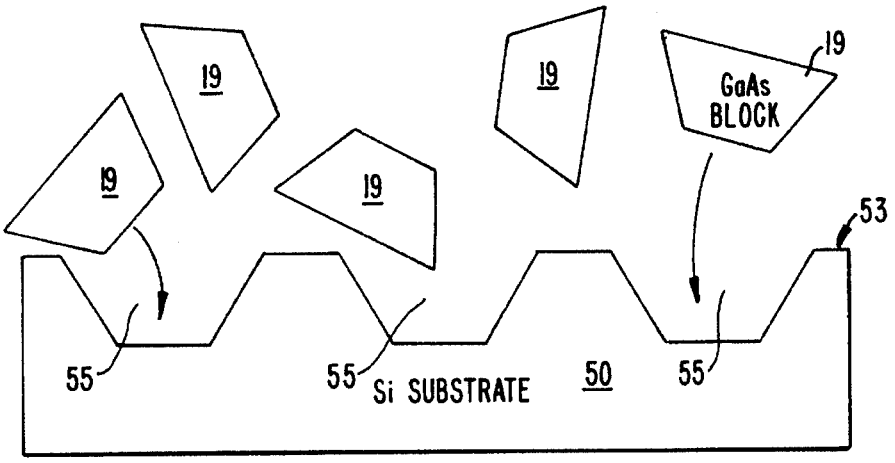
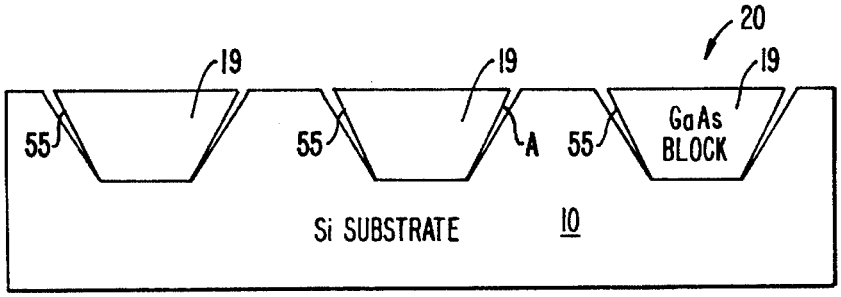
[57] **ABSTRACT**

A method for assembling microstructures onto a substrate through fluid transport. The microstructures being shaped blocks self-align into recessed regions located on a substrate such that the microstructure becomes integral with the substrate **20**, **70**, **90**, **120**, **200**. The improved method includes a step of transferring the shaped blocks into a fluid to create a slurry. Such slurry is then poured evenly over the top surface of a substrate having recessed regions thereon. The microstructure via the shape and fluid tumbles onto the surface of the substrate, self-aligns, and engages into a recessed region.

26 Claims, 9 Drawing Sheets